



Product Data Sheet – SI 100 Lid Seal Adhesive

Description:

SI 100 is a thermally conductive B-stage adhesive. The material has a relatively low coefficient of thermal expansion, high glass transition temperature and good adhesion properties to plastic and ceramic substrates. SI 100 is RoHSA compatible.

Selected Properties (Cured Material):

Color: Cream

Thermal Conductivity: .45 w/m -°k

Glass Transition Temperature: 130°C

Linear Coefficient of Thermal Expansion: (130°C and below) 48×10^{-8}

Recommended Cure Schedule:

30 Minutes @ 175°C

60 Minutes @ 150°C

Note: The above referenced information is for informational purposes only. Spectrum recommends that customers evaluate this product in their own facility for their specific application.

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